CONTROLLED AVALANCHE RECTIFIER DIODES

Also available to BS9333-F004

Diffused silicon diodes in a DO—1 metal envelope, capable of absorbing transients. They are intended for rectifier applications and particularly suited for series operation.

The series consists of the following reverse polarity types (anode to case):

BYX45-600R, BYX45-800R, BYX45-1000R, BYX45-1200R and BYX45-1400R.

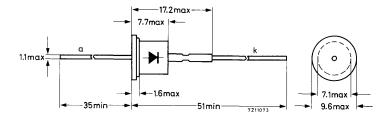
QUICK REFERENCE DATA

		BYX45	-600R	800R	1000R	1200R	1400R	. +-
Crest working reverse voltage Reverse breakdown voltage	V _{RWM} V _{(BR)R}	max.	600 750	800 1000	1000 1250	1200 1450		V V
Average forward current	l _F (AV)	max.			1.5			Α
Non repetitive peak forward current	IFSM	max.			40			Α
Non repetitive peak reverse power	PRSM	max.			2.5			kW

MECHANICAL DATA

Fig. 1 DO-1

Dimensions in mm



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

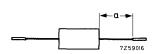
\rightarrow	Voltages		BYX45	-600R	800R	1000R	1200R	1400F	<u> </u>
	Crest working reverse voltage	v_{RWM}	max.	600	800	1000	1200	1400	٧
	Continuous reverse voltage	v_R	max.	600	800	1000	1200	1400	V
	Currents					•			
	Average forward current (averaged over any 20 ms period)			۱F	(AV)	max.		1.5	Α
	R.M.S. forward current			۱F	(RMS)	max.		2.4	Α
	Repetitive peak forward current			۱F	RM	max.		15	Α
	Non-repetitive peak forward current $t = 10$ ms (half sine-wave); $T_j = 150$ with reapplied V_{RWMmax} .	OC prior	to surge;		SM	max.		40	Α
	I^2 t for fusing (t = 10 ms)			l ² 1	t	max.		8	$A^2 s$
	Reverse power dissipation								
	Repetitive peak reverse power dissipat $t = 10 \mu s$ (square-wave; $f = 50 Hz$);		С	PR	RM	max.	8	300	W
	Non-repetitive peak reverse power diss $t = 10 \mu s$ (square-wave)	sipation							
	$T_j = 25$ °C prior to surge				SM	max.		2.5	kW
	T _j = 150 °C prior to surge			PR	SM	max.	8	300	W
	Temperatures								
	Storage temperature			T_{stg}		-55 to +1		150	οС
	Junction temperature			Τį	-	max.		150	οС

THERMAL RESISTANCE

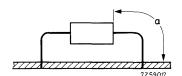
Effect of mounting on thermal resistance Rth j-a

The quoted values apply when no other leads run to the tie-points. If leads of other dissipating components share the same tie-points, the thermal resistance will be higher than that quoted.

- 1. Mounted on solder tags at a lead-length a = 10 mm. $R_{th\ i-a} = 60$ °C/W
- 2. Mounted on solder tags at a = maximum lead-length. $R_{th\ i-a} = 70$ °C/W



- 3. Mounted on printed-wiring board at a = maximum lead-length. $R_{th\ j-a}$ = 80 °C/W
- Mounted on printed-wiring board at a lead-length a = 10 mm. R_{th j-a} = 90 °C/W



SOLDERING AND MOUNTING NOTES

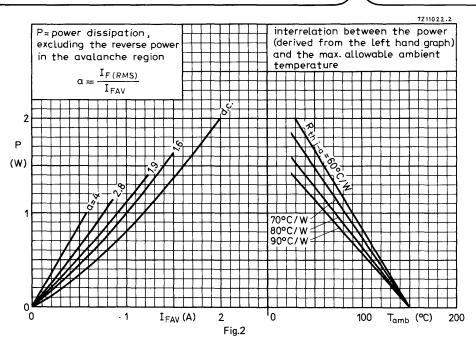
- 1. At a soldering iron or bath temperature of up to 245 °C, the maximum permissible soldering time is 10 s if the joint is 5 mm from the seal, 3 s if it is 1.5 mm from the seal.
- 2. At a temperature between 245 $^{\circ}$ C and 400 $^{\circ}$ C (max.), the joint must be more than 5 mm from the seal and soldering time must not exceed 5 s.
- 3. Leads should not be bent less than 1.5 mm from the seal; exert no axial pull when bending.

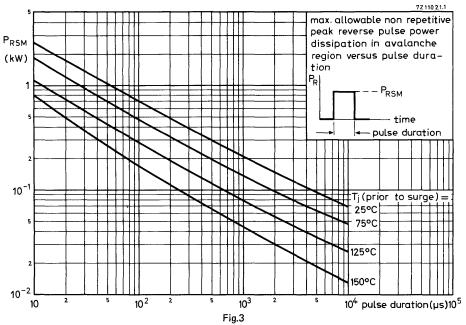
BYX45 SERIES

CHARACTERISTICS

		BYX45-600R		800R 1000R		1200R	1400F	<u> </u>
Forward voltage $I_F = 5 \text{ A}; T_j = 25 ^{\circ}\text{C}$	V _F	<	1.45	1.45	1.45	1.45	1.45	٧*
Reverse avalanche breakdown voltage	V _{(BR)R}	>	750	1000	1250	1450	1650	٧
$I_R = 1 \text{ mA}; T_j = 25 {}^{\circ}\text{C}$		<	2000	2000	2000	2200	2400	٧
Reverse current $V_R = V_{RWMmax}$; $T_i = 125$ °C	I _R	<	100	100	100	100	100	μΑ

^{*}Measured under pulse conditions to avoid excessive dissipation.





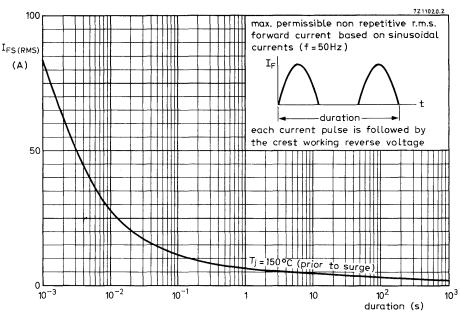


Fig.4

